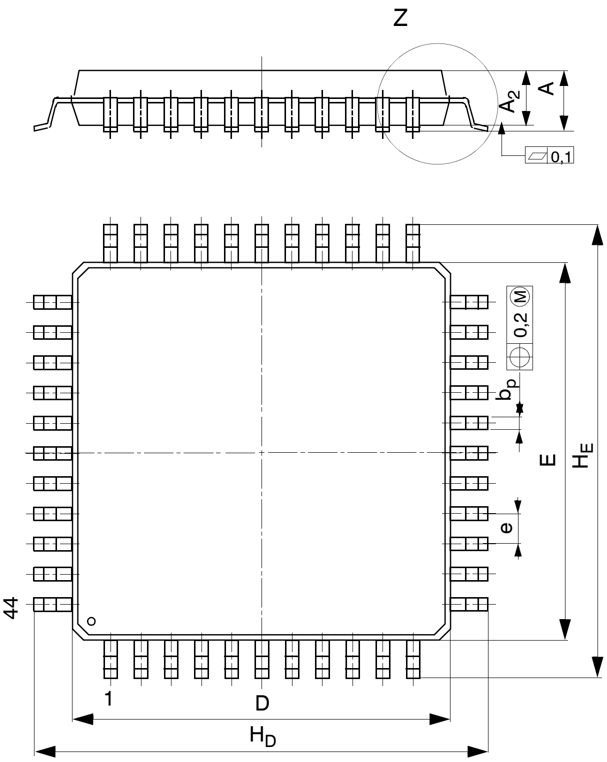
ZMD	**Package LQFP44** **(10 x 10)**	**MDS** **758**

Dimensions in millimetres

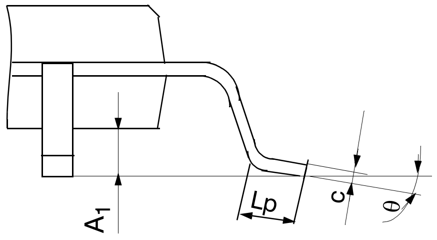
Supersedes
Edition 12.99

Based on JEDEC JEP95: MS-026

1 Dimensions



Detail Z



Dimensions of Sub-Group B1	
e_{nom}	0,80
A_{max}	1,60
b_{Pmin}	0,30
b_{Pmax}	0,45
H_{Emin}	11,85
H_{Emax}	12,15
H_{Dmin}	11,85
H_{Dmax}	12,15
L_{Pmin}	0,45

2 Weight	≤ 0,5 g
3 Package Body Material	Low Stress Epoxy
4 Lead Material	FeNi-Alloy or Cu-Alloy
5 Lead Finish	solder plating
6 Lead Form	Z-bends

Dimensions of Sub-Group C1	
A_{min}	-
A_{1min}	0,05
A_{1max}	0,15
A_{2min}	1,35
A_{2max}	1,45
c_{min}	0,09
c_{max}	0,20
D_{min}*	9,75
D_{max}*	10,25
E_{min}*	9,75
E_{max}*	10,25
θ_{min}	0°
θ_{max}	7°

* without mold-flas

Zentrum Mikroelektronik Dresden AG		
Editor: signed Schoder	Date: 30.04.2002	Doc-No. QS-000758-HD-02
Check signed Marx	Quality signed Gersdorf:	

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Dimensions in millimetres

Supersedes
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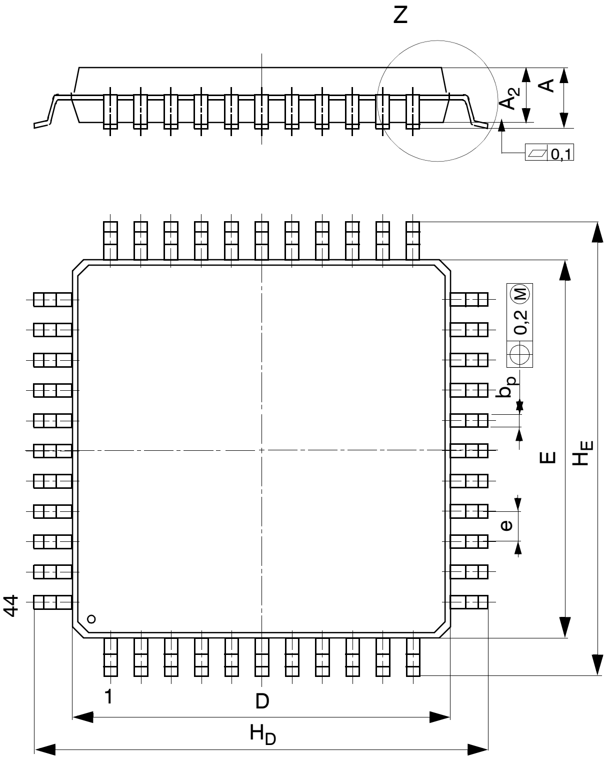
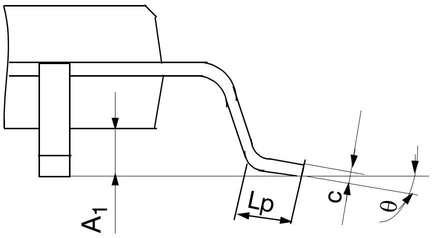
Based on JEDEC JEP95: MS-026

1 Dimensions



Detail Z



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